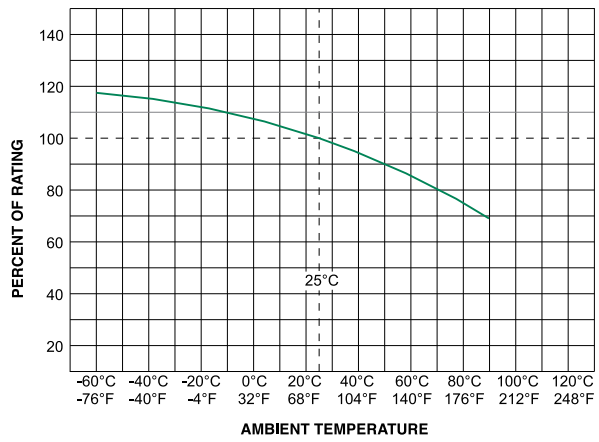
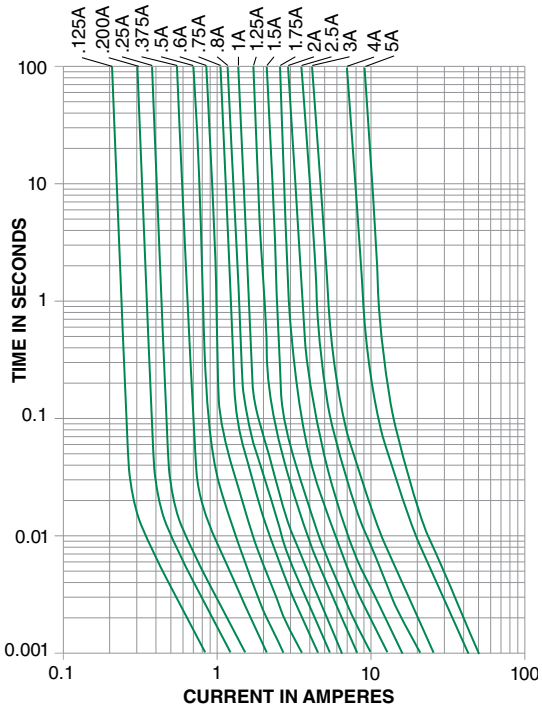
Temperature Rerating Curve

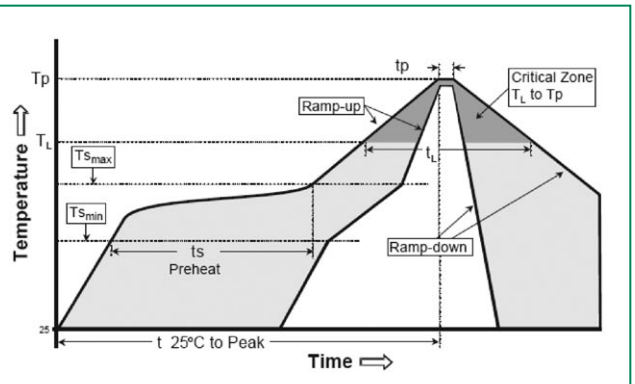


Average Time Current Curves



Soldering Parameters - Wave Soldering

Reflow Condition		Pb – Free assembly
Pre Heat	-Temperature Min ($T_{s(min)}$)	150°C
	-Temperature Max ($T_{s(max)}$)	200°C
	-Time (Min to Max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus Temp (T_L) to peak		5°C/second max
$T_{S(max)}$ to T_L - Ramp-up Rate		5°C/second max
Reflow	-Temperature (T_L) (Liquidus)	217°C
	-Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_P)		$250^{+0/-5}$ °C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		5°C/second max
Time 25°C to peak Temperature (T_P)		8 minutes Max.
Do not exceed		260°C

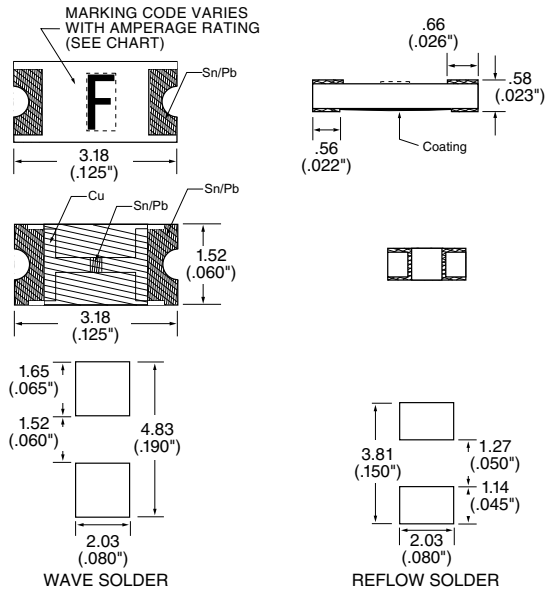


Product Characteristics

Materials	**Body:** Epoxy Substrate **Terminations:** 95% Tin / 5% Lead over Nickel over Copper **Element Cover Coat:** Conformal Coating
Operating Temperature	– 55°C to 90°C. Consult temperature rerating curve chart.
Thermal Shock	Withstands 5 cycles of – 55°C to 125°C

Humidity	MIL-STD-202F Method 103B Condition D
Vibration	Per MIL-STD-202F, Method 201A
Insulation Resistance (After Opening)	Greater than 10,000 ohms.
Resistance to Soldering Heat	Withstands 60 seconds above 200°C and up to 260°C, maximum

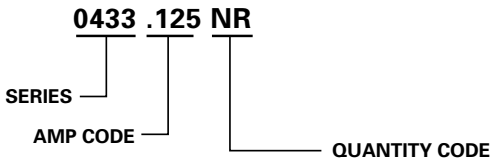
Dimensions



Part Marking System

Amp Code	Marking Code
.125	**B**
.200	**C**
.250	**D**
.375	**E**
.500	**F**
.600	**.6**
.750	**G**
.800	**.8**
001.	**H**
1.25	**J**
01.5	**K**
1.75	**L**
002.	**N**
02.5	**O**
003.	**P**
03.5	**R**
004.	**S**
005.	**T**

Part Numbering System



Packaging

Packaging Option	Packaging Specification	Quantity	Quantity & Packaging Code
Tape & Reel – 8mm tape	EIA RS-481-1 (IEC 286, part 3)	5000	NR